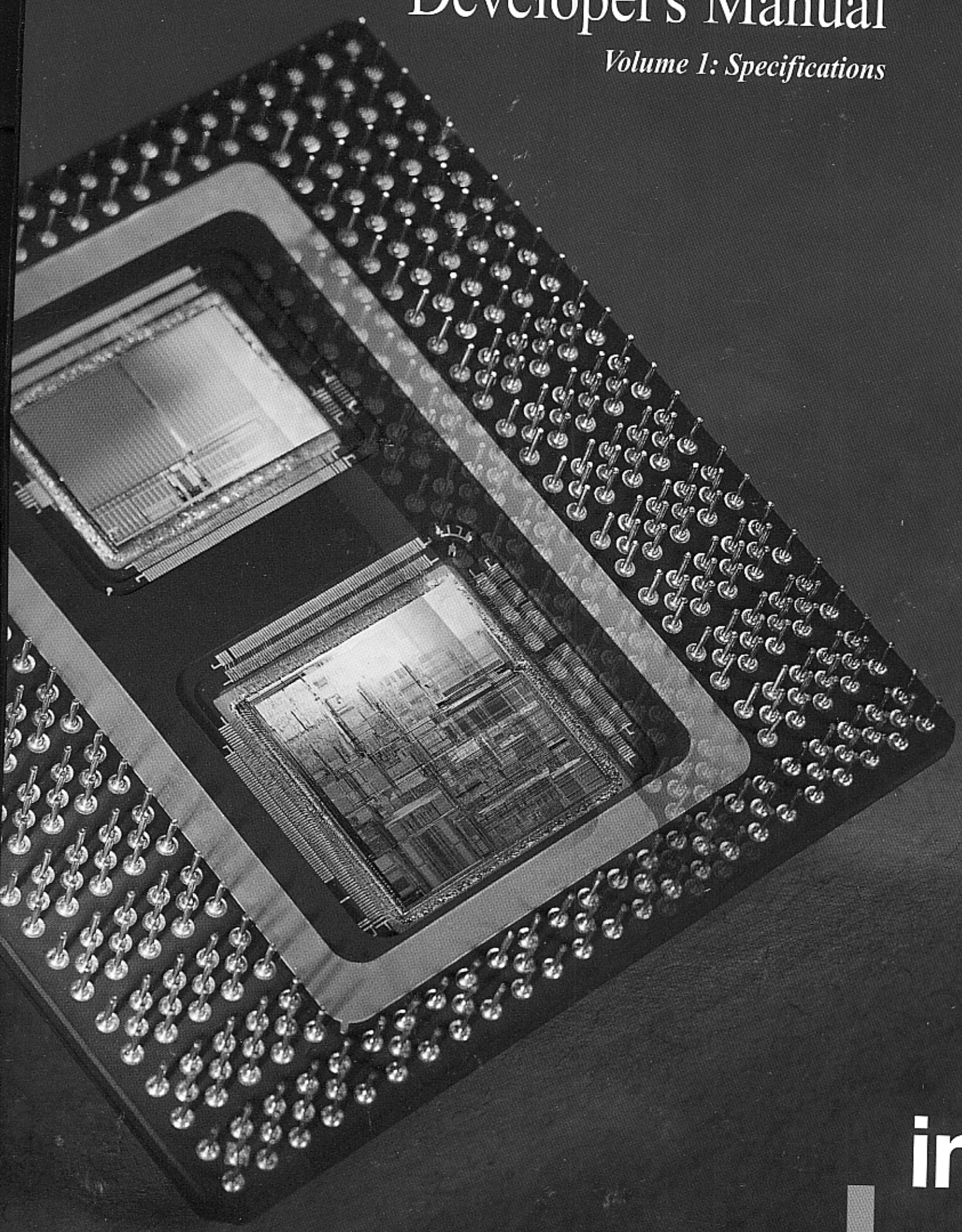
Pentium® Pro Family Developer's Manual

Volume 1: Specifications



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Pentium® Pro Family Developer's Manual

Volume 1: Specifications

NOTE: The *Pentium® Pro Family Developer's Manual* consists of three books: *Specifications*, Order Number 242690; *Programmer's Reference Manual*, Order Number 242691; and the *Operating System Writer's Guide*, Order Number 242692.
Please refer to all three volumes when evaluating your design needs.

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Written for the experienced design engineer, this databook discusses the technical specifications of the Pentium® Pro family of processors ranging from 150MHz to 200 MHz. Electrical, thermal and mechanical data are included in this manual as well as component operation information. Information on design and debug tools, the GTL+ standard and OverDrive® processor specifications are also included in this volume.

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